

Abstract Of The Disclosure

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A method for forming a molded panel comprising a rigid substrate, a cover material, and a localized composite pad. The method comprises providing a molding tool having a first mold and a second mold, the first mold having a cavity; inserting a cover material between the first mold and the second mold; placing a composite pad comprising an impregnable layer and a non-impregnable layer in the cavity of the first mold, wherein the non-impregnable layer is facing the second mold and the impregnable layer is abutting the first mold; introducing resin into the molding tool; and solidifying the resin to form the molded panel whereby the non-impregnable layer of the composite pad is located adjacent the cover material.